

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ROHM AND HAAS ELECTRONIC MATERIALS K.K	03/21/2012
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13370181
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Address Line 4:	MARLBOROUGH, MASSACHUSETTS 01752
ATTORNEY DOCKET NUMBER:	71776-US-NP
NAME OF SUBMITTER:	S. MATTHEW CAIRNS
SIGNATURE:	/S. Matthew Cairns/
DATE SIGNED:	10/12/2014
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, ROHM AND HAAS ELECTRONIC MATERIALS K.K, having a principal place of business at Tennoz Central Tower 2-2-24 Higashi Shinagawa, Shinagawa-ku, Tokyo, Japan, (hereinafter referred to as Assignor), represents and warrants that it is the sole owner of the right, title and interest to certain portion, contributed by its employee(s), of new and useful improvements and/or inventions in "*AG COMPLEXERS FOR TIN-SILVER SOLDER BUMP*", for which a disclosure with the same title was submitted on *September 28, 2011* and assigned Dow reference No71776, for which an application was filed on February 09, 2012 and assigned patent application No. US 13/370181; and

WHEREAS, ROHM AND HAAS ELECTRONIC MATERIALS LLC, located at 455 Forest Street, Marlborough, MA 01752, U.S.A., (hereinafter referred to as the "Assignee"), is desirous of acquiring the entire right, title and interest in and to the same invention, and in and to any applications and any Letters Patent that may issue thereon in any and all countries of world;


NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for the above consideration, the Assignor has assigned and transferred, and does hereby assign and transfer to the Assignee, its successors and assigns, its owned right, title and interest in and to the invention disclosed in said disclosure, in all countries of the world, including the right to file applications and obtain patents for said invention in its own name in said countries and all rights and titles of priority derived from said application in said countries under the terms of any applicable international convention; to have and to hold for the sole and exclusive use and benefit of the Assignee, its successors and assigns, to the full end of the term or terms for which any and all of said Letters Patent for said invention may issue, to the same extent as the Assignor would hold and enjoy if this Assignment had not been made.

The Assignor further agrees to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights, and also agree, at the request of the Assignee, to testify in any legal proceedings, sign all lawful papers, make all lawful oaths, and generally do everything possible to aid said Assignee, its successors and assigns, to obtain, maintain and enforce patent protection for said invention in all countries.

IN WITNESS WHEREOF, the Assignor has caused this Assignment to be executed.

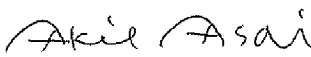
Dated this 21 day of Mar., 2012.

ROHM AND HAAS ELECTRONIC MATERIALS K.K,


Kenya Watanabe
President and Representative Director

(TS)

WITNESS:


Akie Asai

ASSIGNMENT

I, the undersigned, one of the true co-inventors of the following invention, do hereby declare that I have assigned my entire right and title relating to the said invention including the right and title to obtain a patent in Japan as well as in countries outside Japan to the mentioned assignee and/or that I understand and agreed that such entire right and title shall belong to the mentioned assignee. I agree that each co-inventor assigns and transfers his/her right and title to the said invention including the right to obtain a patent to his/her identified assignee respectively.

譲渡証書

私は、下記の発明の共同発明者の一人であるが、今般、日本および日本国外における特許を受ける権利を含む下記の発明にかかる権利の私の持分すべてを下記譲受人に譲渡したこと、および／または、当該私の持分が下記譲渡人に帰属することを了承したことに相違ありません。また、私は、各共同発明者が特許を受ける権利を含む下記発明の各自の持分を各自の譲受人に譲渡することに同意いたします。

INVENTION

Title of the Invention: AG COMPLEXERS FOR TIN-SILVER SOLDER BUMP

発明の名称: 同上

Ref. # / 社内整理番号: DN71776 (ICD002921)

Co-Inventors and Assignee respectively:

Masaaki Imanari / Rohm and Haas Electronic Materials K.K., and

Inho Lee, Elisey Iagodkine, Yi Y Qin and Yu Luo

発明者及び譲受人:

今成 眞明 / ローム・アンド・ハース・電子材料株式会社

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Signature / 署名

今成 眞明 (印)

Date / 日付

2012. 3. 9

ASSIGNEE OF MY RIGHT

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PATENT

RECORDED: 10/12/2014

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